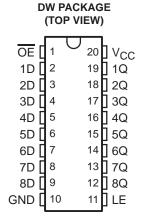
# **Obsolete Device**

# SN74AHCT573-Q1 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCLS541A - SEPTEMBER 2003 - REVISED APRIL 2008

- Qualified for Automotive Applications
- ESD Protection Exceeds 1500 V Per MIL-STD-883, Method 3015; Exceeds 150 V Using Machine Model (C = 200 pF, R = 0)
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17



## description/ordering information

The SN74AHCT573 is an octal transparent D-type latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable  $(\overline{OE})$  input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

 $\overline{\text{OE}}$  does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

## ORDERING INFORMATION<sup>†</sup>

TA	PACKA	\GE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - DW	Tape and reel	SN74AHCT573QDWRQ1	AHCT573QQ1

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

# FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q <sub>0</sub>
Н	Χ	Χ	Z



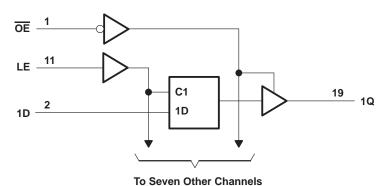
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

SCLS541A - SEPTEMBER 2003 - REVISED APRIL 2008

## logic diagram (positive logic)



# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, $V_{CC}$	0.5 V to 7 V CC + 0.5 V 20 mA ±20 mA ±25 mA ±75 mA 58°C/W
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

# recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
٧ <sub>I</sub>	Input voltage	0	5.5	V
Vo	Output voltage	0	VCC	V
IOH	High-level output current		-8	mA
lOL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-40	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



# SN74AHCT573-Q1 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCLS541A - SEPTEMBER 2003 - REVISED APRIL 2008

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	TEST SOURITIONS	.,	T,	ղ = 25°C	;	BAINI	MAY	LINUT
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
\/a	$I_{OH} = -50 \mu A$	4.5 V	4.4	4.5		4.4		V
Voн	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		V
\/a.	$I_{OL} = 50 \mu A$	4.5 V			0.1		0.1	٧
VOL	$I_{OL} = 8 \text{ mA}$	4.5 V			0.36		0.44	V
lį	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±0.25		±2.5	μΑ
ICC	$V_{I} = 5.5 \text{ V or GND},  I_{O} = 0$	5.5 V			4		40	μΑ
∆l <sub>CC</sub> †	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2.5	10			pF
Co	$V_O = V_{CC}$ or GND	5 V		3	·	·		pF

<sup>†</sup>This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or VCC.

# timing requirements over recommended operating free-air temperature range, $\rm V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

		T <sub>A</sub> = 2	25°C	BAINI	MAY	
		MIN		MIN	MAX	UNIT
t <sub>W</sub>	Pulse duration, LE high	5		5		ns
t <sub>su</sub>	Setup time, data before LE↓	3.5		3.5		ns
th	Hold time, data after LE↓	1.5		1.5		ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	Δ = 25°C	;		BEAV	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH			0 45 5		4.2	6	1	6.5	
<sup>t</sup> PHL	D	Q	C <sub>L</sub> = 15 pF		5.1	7	1	9	ns
<sup>t</sup> PLH		_	0. 45 = 5		4.7	6.5	1	7.5	
<sup>t</sup> PHL	LE	Q	C <sub>L</sub> = 15 pF		5.6	7.5	1	9	ns
<sup>t</sup> PZH	ŌĒ	0	0. 45 = 5		4.1	6.5	1	7	
tPZL	OE	Q	C <sub>L</sub> = 15 pF		5.5	7.5	1	10	ns
<sup>t</sup> PHZ	ŌĒ	0	C. 15 nF		5.5	8	1	11	20
t <sub>PLZ</sub>	OE	Q	C <sub>L</sub> = 15 pF		5.4	8	1	9.5	ns
<sup>t</sup> PLH	D	Q	C: 50 pF		5.2	7	1	7.5	
<sup>t</sup> PHL	U	Q	C <sub>L</sub> = 50 pF		6.1	8	1	10	ns
<sup>t</sup> PLH	LE	Q	C: 50 pF		5.7	7.5	1	8.5	
<sup>t</sup> PHL	LE	Q	C <sub>L</sub> = 50 pF		6.6	8.5	1	10	ns
<sup>t</sup> PZH	ŌĒ	Q	C 50 pF		5.1	7.5	1	8	200
tPZL	UE		C <sub>L</sub> = 50 pF		6.5	8.5	1	11	ns
<sup>t</sup> PHZ	ŌĒ	0	C: - 50 pF		6.7	9	1	12	no
t <sub>PLZ</sub>	UE	Q	C <sub>L</sub> = 50 pF		6.4	9	1	10.5	ns
tsk(o)			C <sub>L</sub> = 50 pF			1.5			ns

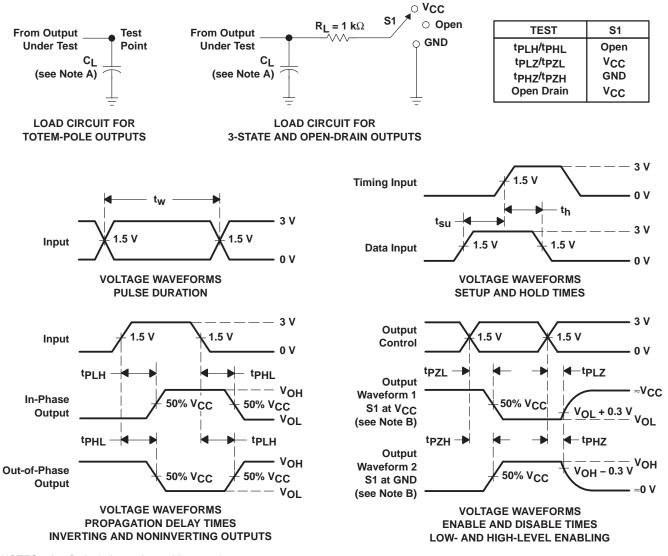
# SN74AHCT573-Q1 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCLS541A - SEPTEMBER 2003 - REVISED APRIL 2008

## operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	16	pF

## PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns,  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





# **PACKAGE OPTION ADDENDUM**

27-Sep-2013

### PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Diawing		u.,	(2)		(3)		(4/5)	
SN74AHCT573QDWRQ1	OBSOLETE	SOIC	DW	20		Green (RoHS	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT573QQ1	
						& no Sb/Br)					

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

### OTHER QUALIFIED VERSIONS OF SN74AHCT573-Q1:



# **PACKAGE OPTION ADDENDUM**

27-Sep-2013

• Military: SN54AHCT573

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

DW (R-PDSO-G20)

## PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



### IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have not been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

#### **Products Applications**

power.ti.com

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

**RFID** www.ti-rfid.com

Power Mgmt

**OMAP Applications Processors** www.ti.com/omap **TI E2E Community** e2e.ti.com

Wireless Connectivity www.ti.com/wirelessconnectivity